Contact Name Title - Contact Product Env-Stewards Product Env-	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name	752-21.1											als and Mfg l	nformati	on	
Semi	upplier Informa	ation													
Title - Contact Name Product Envisewards NA Na Nanufacturing Site Veight* UOM Unit Nanufacturing Proccess Information Nanufacturing Proccess Information NA Nanufacturing Site Veight* NA Nanufacturing Site Nanufacturing Site Na Nanufacturing Site Nanufact	Company name* Company unique ID				ique ID	D Unique ID 1		Jnique ID Auth	e ID Authority			Response Date*			
Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Pr	nsemi											2025-05-14			
Title - Representative Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-	Contact Name			Title - Contact			F	Phone - Contact*				Email - Contact*			
Product Enviro Compliance Requester Item Number Mfr Item Number Effective Date Version Manufacturing Site Weight* UOM Unit TSCBE 67.9 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array	Product-Env-Stewar	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	ntative*	Title - Representative			F	Phone - Representative*			Email - Representative*					
ESIG UFR SMA PN 1A 400V 2025-05-14 TSCBE 67.9 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles and Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 Matter Tin (Sn) - annealed Seconds Seconds	Product-Env-Stewar	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
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Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds			ES1G		UFR SMA PN 1A	400V		2025-05-14		Т	SCBE	67.9)	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds				arminal Rosa	Alloy	STD 020 MSI	Pating	Dank Droo	ace Rody T	mparatur	a May Time at Pools	Tamparatura	Numb	or of Potlow Cya	Jac
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1 1 0 0		me at neals temperature	o during sol	doring is 10-2	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.764	mg	Supplier	Silicon (Si)	7440-21-3		0.6876	mg
			В	Nickel (Ni)	7440-02-0		0.005	mg
			Supplier	Gold (Au)	7440-57-5		0.0011	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0703	mg
Die Attach Solder	2.25	mg	Supplier	Silver (Ag)	7440-22-4		0.0563	mg
			A	Lead (Pb)	7439-92-1	7a	2.0812	mg
			Supplier	Tin (Sn)	7440-31-5		0.1125	mg
Lead Frame	27.5903	mg	Supplier	Iron (Fe)	7439-89-6		0.0331	mg
			Supplier	Copper (Cu)	7440-50-8		27.5489	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0083	mg
Mold Compound-Black	36.69	mg		Metal Hydroxide	proprietary data		1.2842	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.9352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1834	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.352	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.9352	mg
Plating	0.6057	mg	Supplier	Tin (Sn)	7440-31-5		0.6057	mg